Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	(power near (CMOS MOS FET MIS switch$3)) with (IC (integrated near circuit)) with (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:01
L2	8	(("6351031") or ("5475565") or ("6330158") or ("5625536")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/06/17 11:32
L3	0	("module$1").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2005/06/17 11:33
L4	630391	module$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 11:33
L5	91046	4 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L6	8925	5 and (power near2 (chip$1 die$1 IC$1 circuit$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55
L7	327	6 and (flip near chip near bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:02
L8	1048	6 and (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55

L9	531	8 and ((thermal heat) near (dissipat$3 sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:36
L10	413	9 and (resin seal$3 encapsulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L11	116	10 and gate$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 11:39
L12	16	("5227663" | "5371404" | "5641987" | "5785799" | "5834839" | "5866953" | "5872395" | "5891753" | "5977626" | "6069023" | "6150193" | "6191360" | "6201301" | "6229702" | "6316829" | "6462405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 12:25
L13	192	7 and ((thermal heat) near (dissipat$3 sink))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:37
L14	195	7 and ((thermal heat) near (dissipat$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55
L15	162	14 and (resin seal$3 encapsulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:37
L16	24993	5 and (power with (chip$1 die$1 IC$1 circuit$1 device$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L17	2466	16 and (flip near chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:55

L18	1050	17 and ((thermal heat) near (dissipat$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:08
L19	807	18 and (resin seal$3 encapsulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L20	807	19 and (substrate carrier$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:56
L21	339	20 and (flip near chip near bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:57
L22	315	21 and packag$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:58
L23	139	22 and driv$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 12:59
L24	5	("20020049042" | "6072122" | "6114413" | "6320543" | "6630727").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 14:04
L25	2	("6165885" | "6239486").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 14:07
L26	3045	(power near (CMOS MOS FET MIS switch$3)) with (IC (integrated near circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:27
L27	2	26 and (flip near chip near bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07

L28	1228451	(power with (chip$1 die$1 IC$1 circuit$1 device$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L29	149989	28 and (driv$3 near (chip$1 die$1 IC$1 circuit$1 device$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:06
L30	347	29 and (flip near chip near bond$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L31	238	30 and (resin seal$3 encapsulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:07
L32	95	31 and ((thermal heat) near (dissipat$3 sink spreader))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:08
L33	132	(power near (CMOS MOS FET MIS switch$3)) with (driv$3 near (IC (integrated near circuit)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:41
L34	17	33 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:28
L35	4	("5656550" | "5976912" | "6238952" | "6294830").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 15:38
L36	8	("5559364" | "5580466" | "6001671" | "6025650" | "6063139" | "6228676" | "6410363" | "6451627").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/17 15:39
L37	115	33 not 34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/17 15:42

| L38 | 4 | ("5109318" \| "5373418" \| "5375040" \| "5514917").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/06/17 15:46 |